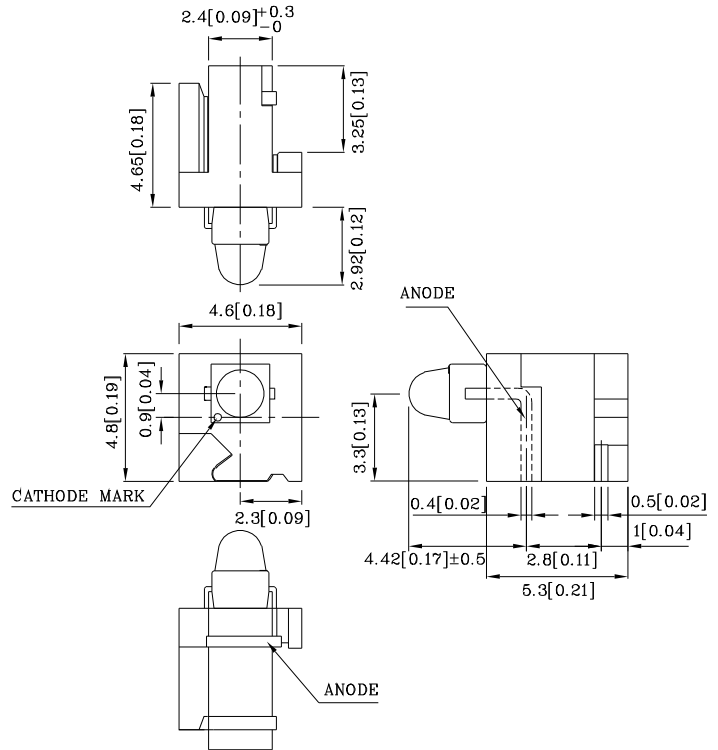


Features

- I.C. COMPATIBLE
- BLACK CASE ENHANCES CONTRAST RATIO
- HOUSING MATERIAL:PPA
- HIGH TEMPERATURE RESISTANT HOUSING
- PACKAGE: 500PCS / REEL .
- RoHS COMPLIANT.



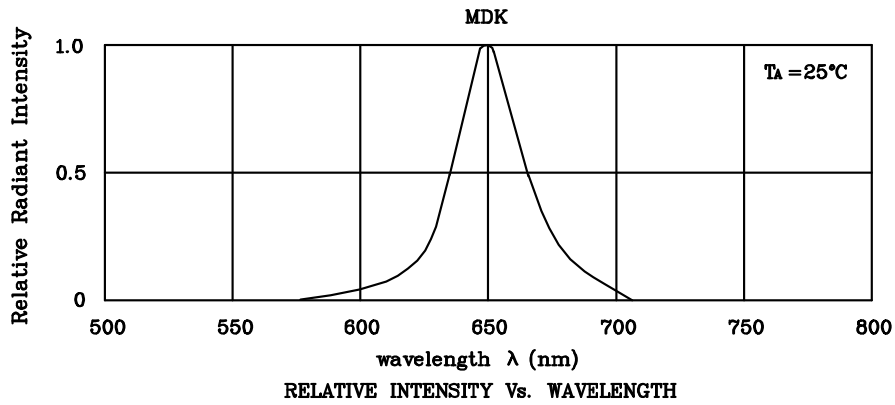
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.1(0.004") unless otherwise noted.

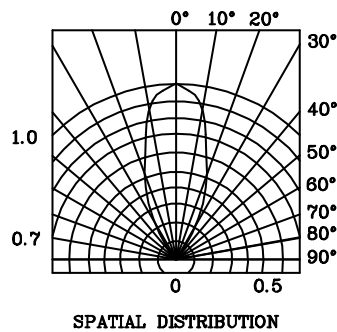
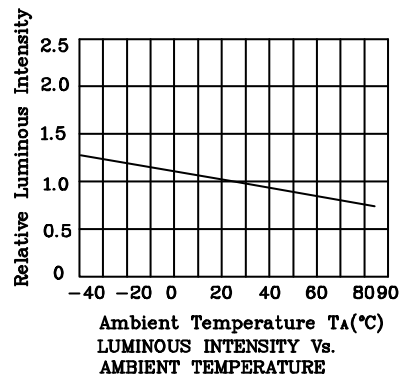
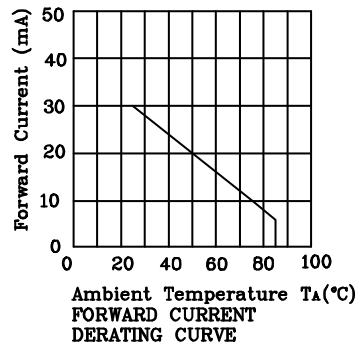
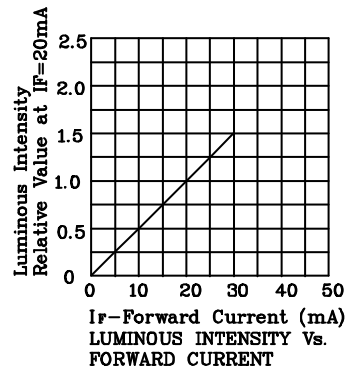
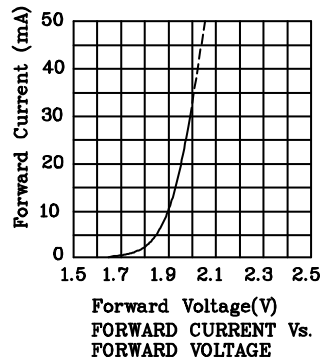
Absolute maximum ratings (TA=25°C)		MDK (InGaAlP)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	185	mA
Power Dissipation	P _T	170	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	

Operating Characteristics (TA=25°C)		MDK (InGaAlP)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V _F	1.95	V
Forward Voltage (Max.) (I _F =20mA)	V _F	2.5	V
Reverse Current (V _R =5V)	I _R	10	uA
Wavelength of Peak Emission (I _F =20mA)	λ _p	650	nm
Wavelength of Dominant Emission (I _F =20mA)	λ _D	635	nm
Spectral Line Full Width At Half-Maximum (I _F =20mA)	Δλ	28	nm
Capacitance (V _F =0V, f=1MHz)	C	35	pF

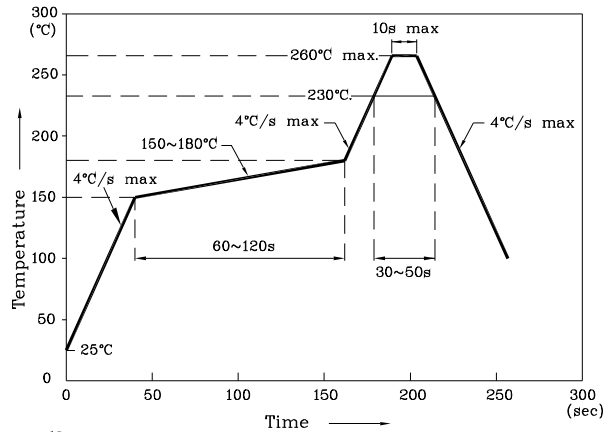
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =20mA) mcd		Wavelength nm λ P	Viewing Angle 2 θ 1/2
				min.	typ.		
XRP1LMDK103D	Red	InGaAlP	Red Diffused	180	377	650	40°



❖ MDK



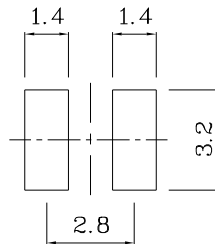
Reflow Soldering Profile For Lead-free SMT Process.



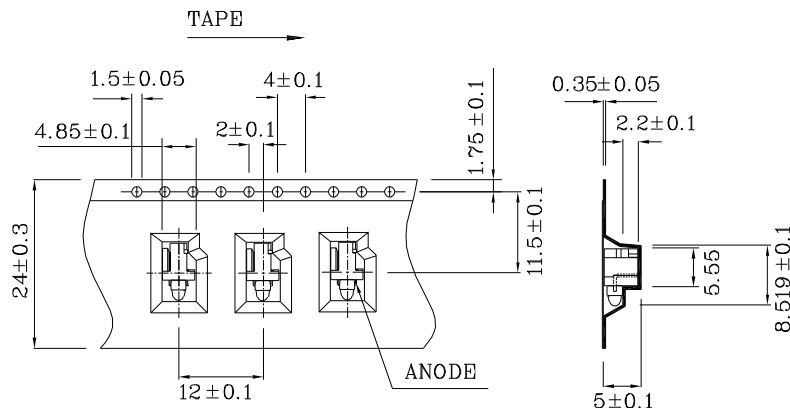
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units : mm;Tolerance:± 0.1)



❖ Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.